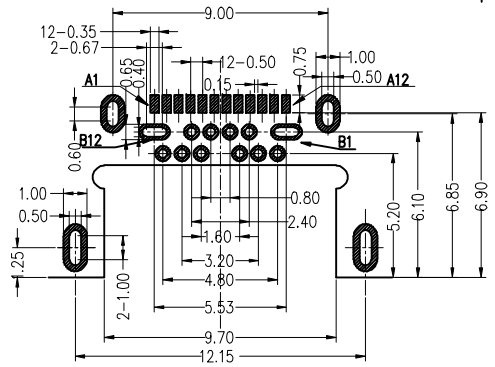
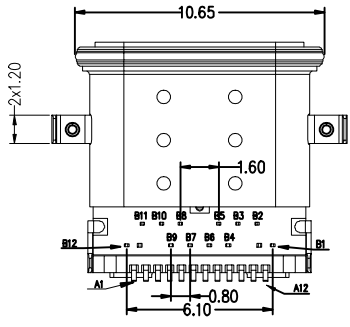
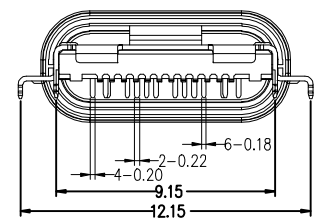
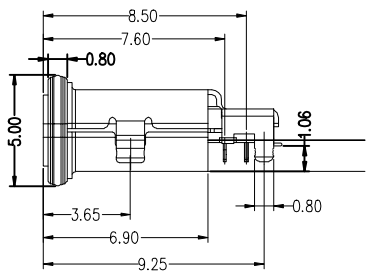
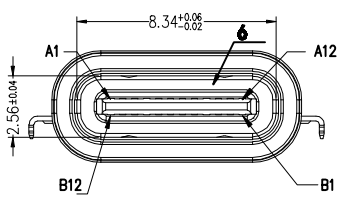
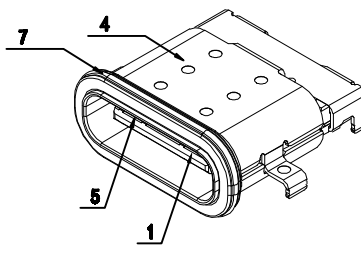
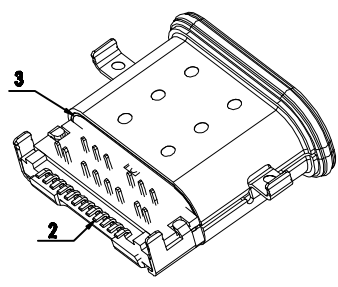
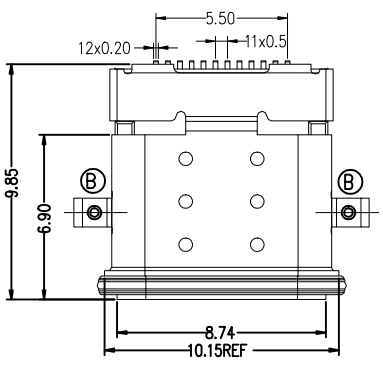


MAPX	MODIFICATION	DATE
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RECOMMEND PCB LAYOUT  
TOL=±0.05

SPECIFICATION:

1.ELECTRICAL:

- 2-1.Contact current rating:5A(Max)
- 2-2.Contact rated vltge:30VAC
- 2-3.Contact resistance:initial:Power Pin 30mohm max, other contacts Pin40mohm max, after durability:change of +10mohm
- 2-4.Insulation resistance:100 Mohm Min
- 2-5.Withstanding strength:100V AC For 1Minute

2.Material & Finish:

Shell :Sus304,50U" Ni plating over all.  
Contact: C7025,3U"min Au plating on conctac area, 30 U" Tin(min) plating on solder area(DIP contact). 1U" Au plating on solder area(SMT contact).  
Ni 30U"min under plating over all.

3:MECHANICAL CHARACTERISTICS:

- 2-1:MATING FORCE:5~20N
- 3-2:UNMATING FORCE:8~20N(INITIAL), 6~20N(AFTER 10000 CYCLES)
- 3-3:FREQUENCE: 200±50 CYCLES /HOUR,10000 CYCLES
- 3-4:OPERATING TEMPERATURE ;-40~80°.
- 4: WATERPROOF: IP-X7.

TABLE A

NO.	DESCRIPTION	MATERIAL	FINISH PLANTED	QTY	REMARKS
7	RING	SILICON	---	1PCS	
6	MID-PLANT	STAINLESS STEEL	---	1PCS	
5	GND-PLANT	STAINLESS STEEL	Ni/SN Plated	1PCS	
4	SHELL	STAINLESS STEEL	---	1PCS	
3	INNER SHELL	STAINLESS STEEL	Ni Plated	1PCS	
2	CONTACT	COPPER ALLOY	Au/Ni Plated	2SET	
1	HOUSING	PA46	BLACK	1PCS	

TABLE B

A1	GND	B12	GND
A2	SSTXP1	B11	SSRXP1
A3	SSTXN1	B10	SSRXN1
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	DP1	B7	DN2
A7	DN1	B6	DP2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A10	SSRXN2	B3	SSTXN2
A11	SSRXP2	B2	SSTXP2
A12	GND	B1	GND
PIN	SIGNAL NAME	PIN	SIGNAL NAME

**产品图**  
PRODUCT CHART DWG  
公差一览表  
TOLERANCE UNLESS OTHERWISE

X	±0.30 X	±5.°
.X	±0.25 .X	±2.°
.XX	±0.15 .XX	±1.°
.XXX	±0.10 .XXX	±0.5°

# 深圳市精拓金电子有限公司

单位 UNITS	MM	制图 DRAWING	YANG	制图料号 PRODUCT PART NO.	918-418K582A840000
比例 SCALE	1:1	审核 CHKD	郭志富	产品名称 PRODUCT NO.	TYPE-C3.1沉板1.1防水母座双包壳L9.85四脚插板DIP*2+SMT 24PIN
日期 DATE	2019. 11. 23	核准 APPD	黄国荣	角法 VIEW	版本 VER
					A0